

ATTORNEY DOCKET NO.: 6720.0064

DECLARATION/POWER OF ATTORNEY

As a below-named inventor, I hereby declare that my residence, post office address, and citizenship are as stated below next to my name; that I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SUBSTRATE-BIASED SILICON DIODE FOR ELECTROSTATIC DISCHARGE PROTECTION AND FABRICATION METHOD

The specification of which is attached.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. § 1.56(a).

I hereby claim foreign priority benefits under 35 U.S.C. § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Country	Application Number	Date of Filing	Priority Claimed

I hereby claim the benefit under 35 U.S.C. § 120 of any U.S. application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior U.S. application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose material information as defined in 37 C.F.R. § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international date of this application:

Application Number	Date of Filing	Status (patented/pending/abandoned)

I hereby appoint the following attorneys to prosecute this application and transact all business in the U.S. Patent and Trademark Office connected therewith: Finnegan, Henderson, Farabow, Garrett & Dunner, L.L.P., Reg. No. 22,540; Douglas B. Henderson, Reg. No. 20,291; Ford F. Farabow, Jr., Reg. No. 20,630; Arthur S. Garrett, Reg. No. 20,338; Donald R. Dunner, Reg. No. 19, 073; Brian G. Brunsvold, Reg. No. 22,593; Tipton D. Jennings, IV, Reg. No. 20,645; Jerry D. Voight, Reg. No. 23,030; Laurence R. Hefter, Reg. No. 20,827; Kenneth E. Payne, Reg. No. 23,098; Herbert H. Mintz, Reg. No. 26,691; C. Larry O'Rourke, Reg. No. 26,014; Albert J. Santorelli, Reg. No. 22,610; Michael C. Elmer, Reg. No. 25,857; Richard H. Smith, Reg. No. 20,609; Stephen L. Peterson, Reg. No. 26,325; John M. Romary, Reg. No. 26,331; Bruce C. Zotter, Reg. No. 27,680; Dennis P. O'Reilly, Reg. No. 27,932; Allen M. Sokal, Reg. No. 26,695; Robert D. Bajefsky, Reg. No. 25,387; Richard L. Stroup, Reg. No. 28,478; David W. Hill, Reg. No. 28,220; Thomas L. Irving, Reg. No. 28,619; Charles E. Lipsey, Reg. No. 28,165; Thomas W. Winland, Reg. No. 27,605; Basil J. Lewis, Reg. No. 28,818; Martin I. Fuchs, Reg. No. 28,508; Barry W. Graham, Reg. No. 29,924; Thomas H. Jenkins, Reg. No. 30,857; E. Robert Yoches, Reg. No. 30,120; Susan H. Griffen, Reg. No. 30,907; Richard B. Racine, Reg. No. 30,415; Robert E. Converse, Reg. No. 27,432; Christopher P. Foley, Reg. No. 31,354; Clair X. Mullen, Jr., Reg. No. 20,348; John C. Paul, Reg. No. 30,413; David M. Kelly, Reg. No. 30,953; Kenneth J. Meyers, Reg. No. 25,146; Carol P. Einaudi, Reg. No. 32,220; Walter Y. Boyd, Jr., Reg. No. 31,738; Steven M. Anzalone, Reg. No. 32,095; Jean B. Fordis, Reg. No. 32,984; Barbara Clarke McCurdy, Reg. No. 32,120; James K. Hammond, Reg. No. 31,964; Richard V. Burgujian, Reg. No. 31,744;

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

CHYH-YIH CHANG

FULL NAME OF SOLE OR FIRST INVENTOR

Chyh-Yih Chang
INVENTOR'S SIGNATURE

Dec. 13, 2000
DATE

Hsinchuang, Taiwan R.O.C.

RESIDENCE

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MING-DOU KER

FULL NAME OF SECOND INVENTOR

Ming Dou Ker
INVENTOR'S SIGNATURE

Dec. 13, 2000
DATE

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ASSIGNMENT

WHEREAS I/We, the below named inventor(s), hereinafter referred to as Assignor(s), have made an invention entitled SUBSTRATE-BIASED SILICON DIODE FOR ELECTROSTATIC DISCHARGE PROTECTION AND FABRICATION METHOD for which I/We executed an application for United States Letters Patent concurrently herewith; and

WHEREAS, Industrial Technology Research Institute, a corporation of Taiwan whose post office address is Bldg. 51, 195-11 Sec. 4, Chung Hsing Road, Chutung, Hsinchu, Taiwan 310 R.O.C. (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/We, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application to insert here in parentheses (Application No. _____ filed _____) the filing date and application number of said application when known.

CHYH-YIH CHANG

FULL NAME OF SOLE OR FIRST INVENTOR

Chyh-Yih Chang Dec. 13, 2000

INVENTOR'S SIGNATURE

DATE

MING-DOU KER

FULL NAME OF SECOND INVENTOR

Ming-Dou Ker

INVENTOR'S SIGNATURE

Dec. 13, 2000

DATE